Preferred Device

Dual Series Schottky Barrier Diodes

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

Features

- Extremely Fast Switching Speed
- Low Forward Voltage -0.35 V (Typ) @ $I_F = 10 \text{ mAdc}$
- Pb-Free Package is Available

MAXIMUM RATINGS (T_J = 125°C unless otherwise noted)

Rating	Symbol	Value	Unit
Reverse Voltage	V _R	30	V
Forward Power Dissipation @ T _A = 25°C Derate above 25°C	P _F	240 1.9	mW mW/°C
Forward Current (DC)	I _F	200 Max	mA
Junction Temperature	T_J	-55 to 125	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	525	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

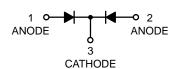
1. FR-5 board with minimum mounting pad.



ON Semiconductor®

http://onsemi.com

30 VOLT DUAL COMMON CATHODE SCHOTTKY BARRIER DIODES



MARKING DIAGRAM



SC-89 CASE 463C STYLE 3



5C = Device Code M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

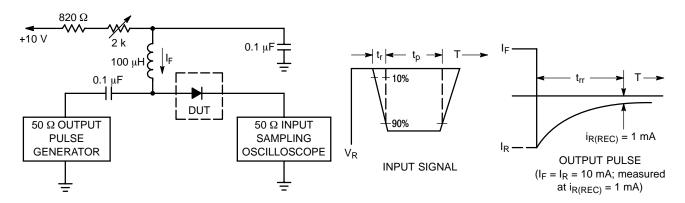
Device	Package	Shipping [†]
BAT54CXV3T1	SC-89	3000 / Tape & Reel
BAT54CXV3T1G	SC-89 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted) (EACH DIODE)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage $(I_R = 10 \mu A)$	V _{(BR)R}	30	-	-	V
Total Capacitance (V _R = 1.0 V, f = 1.0 MHz)	C _T	-	7.6	10	pF
Reverse Leakage (V _R = 25 V)	I _R	-	0.5	2.0	μAdc
Forward Voltage (I _F = 0.1 mAdc)	V _F	-	0.22	0.24	Vdc
Forward Voltage (I _F = 30 mAdc)	V _F	-	0.41	0.5	Vdc
Forward Voltage (I _F = 100 mAdc)	V _F	-	0.52	0.8	Vdc
Reverse Recovery Time $(I_F = I_R = 10 \text{ mAdc}, I_{R(REC)} = 1.0 \text{ mAdc}, Figure 1)$	t _{rr}	-	-	5.0	ns
Forward Voltage (I _F = 1.0 mAdc)	V _F	-	0.29	0.32	Vdc
Forward Voltage (I _F = 10 mAdc)	V _F	-	0.35	0.40	Vdc
Forward Current (DC)	I _F	_	_	200	mAdc
Repetitive Peak Forward Current	I _{FRM}	-	-	300	mAdc
Non-Repetitive Peak Forward Current (t < 1.0 s)	I _{FSM}	-	-	600	mAdc



Notes: 1. A 2.0 $k\Omega$ variable resistor adjusted for a Forward Current (I_F) of 10 mA.

2. Input pulse is adjusted so $I_{R(peak)}$ is equal to 10 mA.

3. $t_p \gg t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit

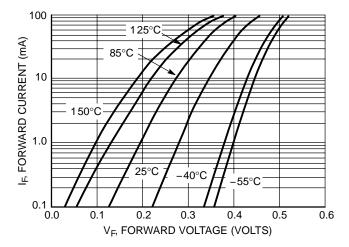


Figure 2. Forward Voltage

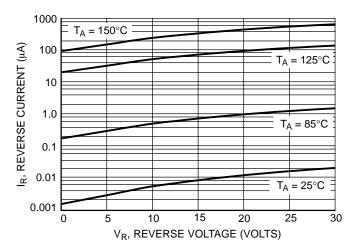


Figure 3. Leakage Current

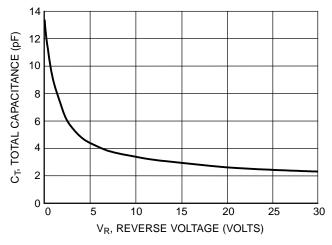
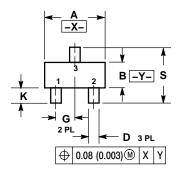
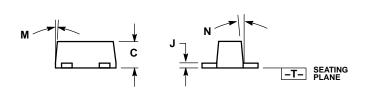


Figure 4. Total Capacitance

PACKAGE DIMENSIONS

SC-89, 3-LEAD CASE 463C-03 **ISSUE C**





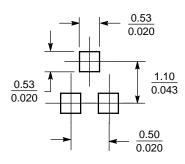
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL
- 463C-01 OBSOLETE, NEW STANDARD 463C-02.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.60	1.70	0.059	0.063	0.067
В	0.75	0.85	0.95	0.030	0.034	0.040
С	0.60	0.70	0.80	0.024	0.028	0.031
D	0.23	0.28	0.33	0.009	0.011	0.013
G	0.50 BSC			0.020 BSC		
Н	0.53 REF			0.021 REF		
J	0.10	0.15	0.20	0.004	0.006	0.008
K	0.30	0.40	0.50	0.012	0.016	0.020
L	1.10 REF			0.043 REF		
M			10			10
N			10			10
S	1.50	1.60	1.70	0.059	0.063	0.067

STYLE 3: PIN 1. ANODE 2. ANODE

3. CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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